

Thin Film Chip Inductors

Type KL73 0805

ISO 9001:2000
CERTIFIED
TS-16949
CERTIFIED

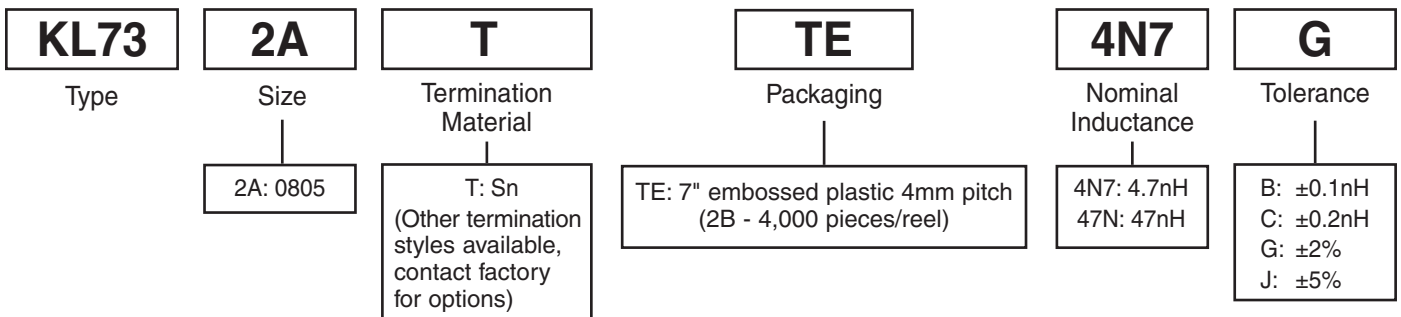
1. Scope

This specification applies to Thin Film Chip Inductors (KL73) 2A size produced by KOA Corporation.

2. Type Designation

The type designation shall be the following form:

New Type



3. Rating

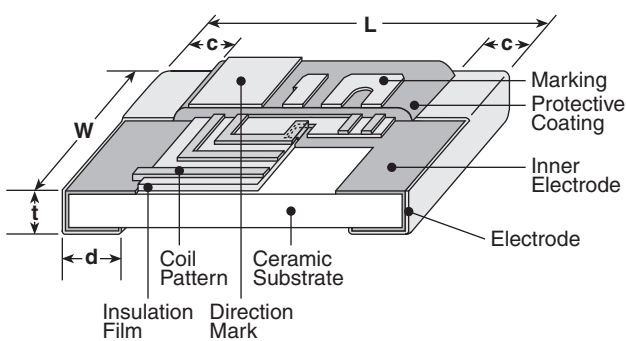
Item	Ratings
Nominal Inductance Range (nH)	1.0 ~ 82 (E-12 series)
Inductance Tolerance	± 2%, ± 5% (± 0.2nH: Under 4.7nH)
Quality Factor (typ.)	10 ~ 25
Self Resonant Frequency (typ.) (MHz)	600 ~ 13,000
DC Resistance (typ.) (Ω)	0.25 ~ 5.00
Allowable Current (max.) (mA)	150 ~ 900
Operating Temperature Range (°C)	-40°C ~ +85°C
Storage Temperature Range (°C)	-40°C ~ +125°C

Rating Table

Part Designation	Inductance (nH)	Inductance Tolerance	Quality Factor Minimum	Self Resonant Frequency Minimum (MHz)	DC Resistance Maximum (Ω)	Allowable DC Current Maximum (mA)	Measured Frequency (MHz)		
KL732ATTE1N0*	1.0	C: $\pm 0.2\text{nH}$	20	13000	0.25	900	500		
KL732ATTE1N2*	1.2			10000					
KL732ATTE1N5*	1.5								
KL732ATTE1N8*	1.8			9000					
KL732ATTE2N2*	2.2							8000	
KL732ATTE2N7*	2.7								
KL732ATTE3N3*	3.3		25	25		6000		0.50	700
KL732ATTE3N9*	3.9					5000			
KL732ATTE4N7*	4.7								
KL732ATTE5N6*	5.6					4000			
KL732ATTE6N8*	6.8	3000							
KL732ATTE8N2*	8.2			2000					
KL732ATTE10N*	10	2500							
KL732ATTE12N*	12				1500				
KL732ATTE15N*	15	1000							
KL732ATTE18N*	18				800				
KL732ATTE22N*	22	700							
KL732ATTE27N*	27		600						
KL732ATTE33N*	33	500							
KL732ATTE39N*	39		400						
KL732ATTE47N*	47	300							
KL732ATTE56N*	56		250						
KL732ATTE68N*	68	200							
KL732ATTE82N*	82		150						
		10							

* Add tolerance character (B, C, G, J)

4. Dimensions



Type (Inch Size Code)	Dimensions inches (mm)				
	L	W	c	d	t
2A (0805)	.079 \pm .008 (2.0 \pm 0.2)	.049 \pm .008 (1.25 \pm 0.2)	.016 \pm .008 (0.4 \pm 0.2)	.012 \pm .004 (0.3 \pm 0.2)	.02 \pm .004 (0.5 \pm 0.1)

5. Marking

5-1 Coating and Marking Color

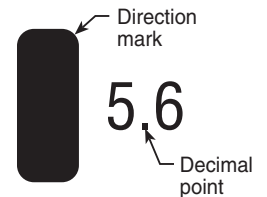
Coating color: Dark blue
Direction mark color: Yellow

5-2 Marking Method

Inductance value shall be indicated to two letters marking, including decimal point.

(Example of marking)

2.2 \rightarrow 2.2nH
5.6 \rightarrow 5.6nH
10 \rightarrow 10nH
47 \rightarrow 47nH



6. Characteristics

6-1 Test Condition

Unless otherwise specified, the standard range of atmospheric conditions for marking measurements and tests is as follows:

Ambient temperature: $20 \pm 15^\circ\text{C}$
 Relative humidity: $65 \pm 20\%$

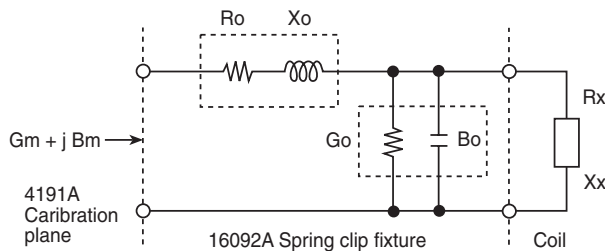
If there may be any doubt on results, measurements shall be made within the following limits:

Ambient temperature: $20 \pm 2^\circ\text{C}$
 Relative humidity: $65 \pm 5\%$

6-2 Measurement Method of L and Q

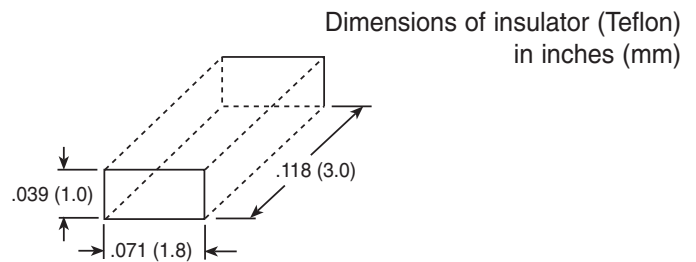
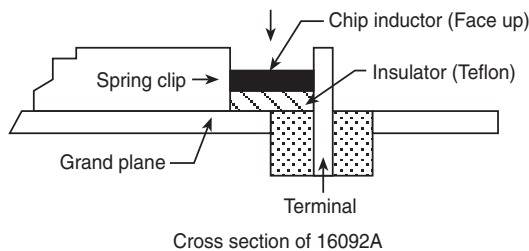
Test equipment: Hewlett Packard RF Impedance analyzer 4191A
 Fixture: Hewlett Packard Test fixture 16092A
 Measuring frequency: 500 MHz/1.0nH ~ 22nH (1.0nH ~ 15nH)
 200 MHz/27nH ~ 100nH (18nH ~ 27nH)

1. Perform auto-calibration to the HP4191A .275" (7mm) unknown connector connected to $0\Omega/0\text{S}/50\Omega$ standard terminations.
2. Connected the test fixture 16092A.
 Measure the open circuit admittance (G_o, B_o), and the short circuit impedance (R_o, X_o).



$G_m + jB_m$: Measured admittance [S]
 $R_o + jX_o$: Residual impedance [Ω]
 $G_o + jB_o$: Stray admittance [S]
 $R_x + jX_x$: Unknown impedance [Q]

3. Set pattern up and ground side to direction mark on insulator.
 Measure admittance (G_m, B_m).



4. The L and Q value shall be given the following equation. (Compensated calculation)

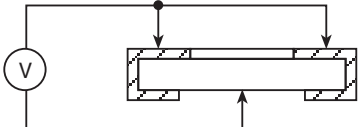
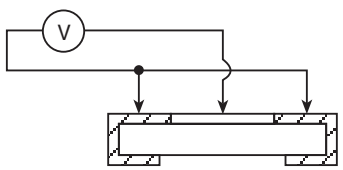
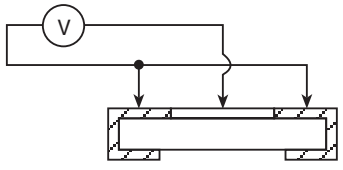
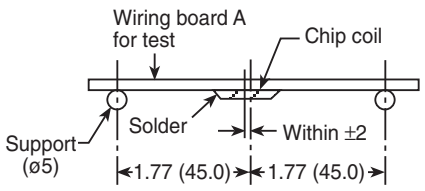
$$R_x = \frac{G_m - G_o}{(G_m - G_o)^2 + (B_m - B_o)^2} - R_o$$

$$X_x = \frac{B_o - B_m}{(G_m - G_o)^2 - (B_m - B_o)^2} - X_o$$

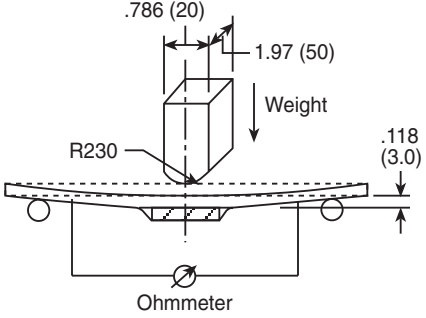
$$L = \frac{X_x}{2\pi f}, \quad Q = \frac{X_x}{R_x}$$

L: Inductance of coil
 Q: Quality factor of coil
 f: Measuring frequency

7-3 Characteristics

Item	Requirement	Test Method
Insulation resistance	More than 10^4 M Ω	DC 500V, 1 minute between both terminals and center of reverse side. 
	More than 10^3 M Ω	DC 500V, 1 minute Between both terminals and center of protection coating. 
Dielectric withstanding voltage	Without distinct damage	DC 500V, 1 minute Between both terminals and center of protection coating. 
Terminal strength	Δ R/R: Within $\pm 1\%$ Δ L/L: Within $\pm 2\%$ Δ Q/Q: Within $\pm 20\%$ No mechanical damage by cracks or stripping, etc.	Soldered chip on wiring board A for test is to be bent down to .118" (3 mm) as below drawing. (Set condition) Dimensions in inches (mm) 

7-3 Characteristics (continued)

Item	Requirement	Test Method
		 <p style="text-align: center;">Dimensions in inches (mm)</p>
Vibration	Δ L/L: Within $\pm 2\%$ Δ Q/Q: Within $\pm 20\%$ Without distinct damage in appearance and construction	Inflict 2 hours in each direction of X, Y, Z at vibration of 10 ~ 55Hz, amplitude .059 (1.5)
Resistance to solder heat	Δ L/L: Within $\pm 2\%$ Δ Q/Q: Within $\pm 20\%$ Without distinct damage in appearance and construction	$260 \pm 5^\circ\text{C}$, 10 ± 1 second
Solderability	95% of the terminal should be covered with new solder	$230 \pm 5^\circ\text{C}$, 3 ± 0.5 second
Shock resistance	Δ L/L: Within $\pm 2\%$ Δ Q/Q: Within $\pm 20\%$ Without distinct damage in appearance and construction	Inflict the impulse 3 times to both directions (total 18 times) along perpendicular axis that test condition 100G, 6 months
Low temperature operation	Δ L/L: Within $\pm 2\%$ Δ Q/Q: Within $\pm 20\%$ Without distinct damage in appearance and construction	$-40^\circ\text{C} \pm 3^\circ\text{C}$, $1,000 \pm 4$ hours
Heat resisting property	Δ L/L: Within $\pm 2\%$ Δ Q/Q: Within $\pm 20\%$ Without distinct damage in appearance and construction	$125^\circ\text{C} \pm 2^\circ\text{C}$, $1,000 \pm 4$ hours
Temperature cycling	Δ L/L: Within $\pm 2\%$ Δ Q/Q: Within $\pm 20\%$ Without distinct damage in appearance and construction	$-40 \pm 3^\circ\text{C}$, 30 minutes/ $125 \pm 2^\circ\text{C}$, 30 minutes 100 cycles

7-3 Characteristics (continued)

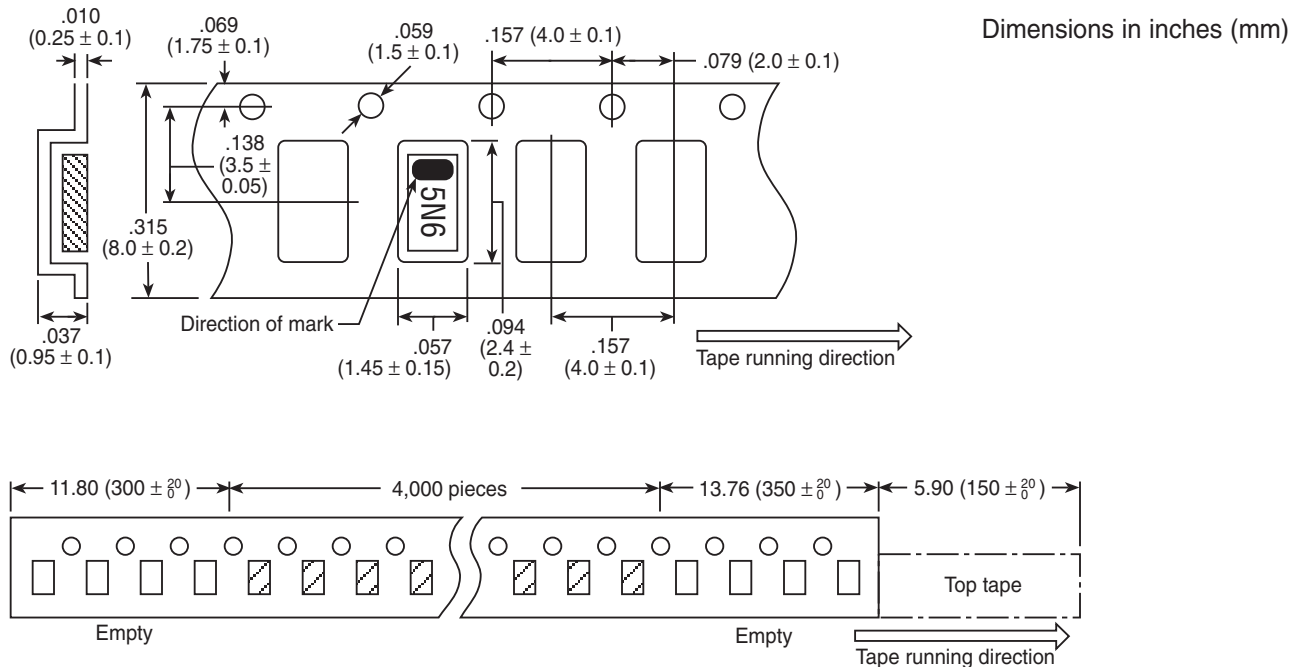
Item	Requirement	Test Method
Humidity	Δ L/L: Within $\pm 2\%$ Δ Q/Q: Within $\pm 20\%$ Without distinct damage in appearance and construction. Insulation resistance: more than $50M\Omega$	$40 \pm 2^\circ\text{C}$, 90 ~ 95% RH $1,000 \pm 4$ hours
Resistance to solvent	Δ L/L: Within $\pm 2\%$ Δ Q/Q: Within $\pm 20\%$ Without distinct damage in appearance, construction and marking	Immerse 30 ± 5 seconds in the reagent ($20 \sim 25^\circ\text{C}$) of JIS K 8839 (1995)

8. Packaging

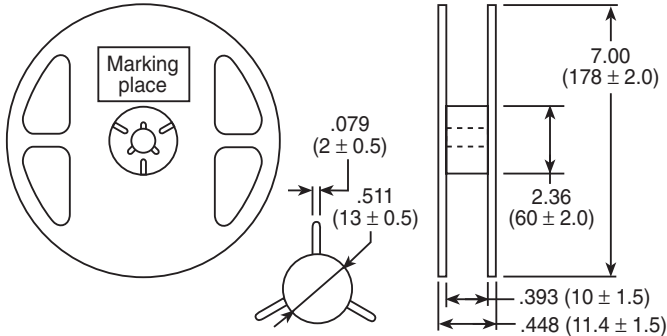
8-1 Taping

The tapes for taping shall be embossed carrier tapes of .315" (8 mm) width and .157" (4 mm) pitches. The standard quantity per reel shall be 4,000 pieces.

(1) Dimensions of carrier tape



(2) Reel dimensions



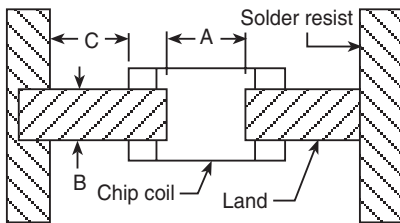
Dimensions in inches (mm)

(Marking item)

- (1) Type designation
- (2) Nominal inductance
- (3) Quantity
- (4) Production lot number
- (5) Manufacturer's name

9. Recommended Soldering Condition

9-1 Dimensions of Standard Land

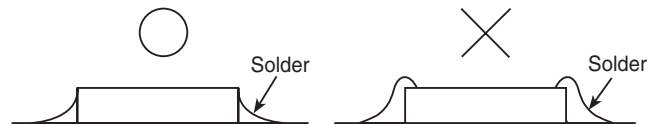


Dimensions in inches (mm)

Size	A	B	C
2A	.047 ~ .055 (1.2 ~ 1.4)	.035 ~ .051 (0.9 ~ 1.3)	.016 ~ .031 (0.4 ~ 0.8)

9-2 Soldering Condition

Reflow soldering should be done at 240°C within 20 seconds. Flow soldering should be done at 260°C within 10 seconds. Please use suitable solder quantity, too much solder may affect performance of product.



10. Recommended Washing Condition

Isopropyl alcohol and methyl alcohol used for the washing process will not affect the part performance. Ultrasonic cleaning should be changed to condition for size of printed wiring board and type of oscillator. Overpowering of ultrasonic cleaning will cause problems according to resonant phenomenon. Condition of ultrasonic cleaner should be confirmed prior to use.

We recommend the following conditions:

- Ultrasonic power: Within 20W/1
- Cleaning times: Within 5 minutes

11. Storage

Chip inductors should not be stored under high temperature and high humidity conditions. In particular, do not store **taping** where it is exposed to heat or direct sunlight. Otherwise, the packing material may be deformed, causing problems during mounting.